



RC2 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 50.41%	Copper (Cu)	7440-50-8	681.460	99.9792	503,968.9
	Phosphorus (P)	7723-14-0	0.007	0.0010	5.0
	Arsenic (As)	7440-38-2	0.007	0.0010	5.0
	Tin (Sn)	7440-31-5	0.007	0.0010	5.0
	Oxygen (O)	7782-44-7	0.003	0.0005	2.5
	Sulfur (S)	7704-34-9	0.082	0.0120	60.5
	Iron (Fe)	7439-89-6	0.004	0.0007	3.3
	Nickel (Ni)	7440-02-0	0.002	0.0003	1.5
	Bismuth (Bi)	7440-69-9	0.012	0.0018	8.9
	Antimony (Sb)	1309-64-4	0.012	0.0018	8.9
	Lead (Pb)	7439-92-1	0.003	0.0005	2.5
	Zinc (Zn)	7440-66-6	0.002	0.0003	1.5
	Total			681.60	
Solder Wafer 0.53%	Lead (Pb)	7439-92-1	6.66	92.50	4,925.4
	Tin (Sn)	7440-31-5	0.36	5.00	266.2
	Silver (Ag)	7440-22-4	0.18	2.50	133.1
	Total			7.20	
Chip 0.50%	Silicon (Si)	7440-21-3	6.80	100.00	5,028.9
	Total			6.80	
Case 22.04%	Epoxy	25928-94-3	298.00	100.00	220,383.8
	Total			298.00	
Potting 26.11%		25928-94-3	353.00	100.00	261,058.6
	Total			353.00	
Plating 0.41%	Tin (Sn)	7440-31-5	5.59	100.00	4,130.3
	Total			5.59	
Total mass (mg)			1,352.19		